

## 500V 18A N-channel Enhancement Mode Power MOSFET

### Description

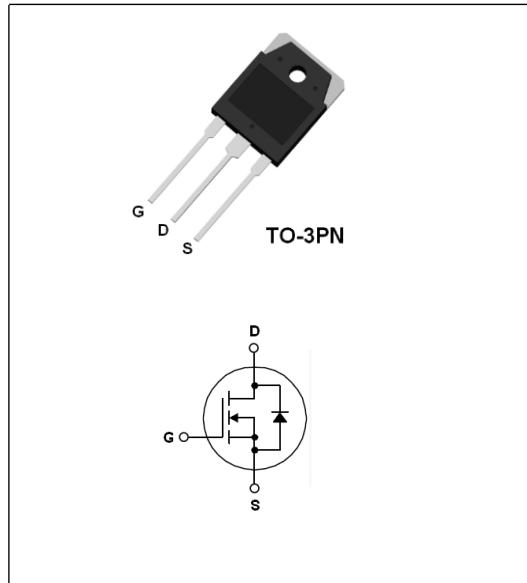
The AKT18N50N is an N-Channel enhancement mode power MOSFET, it has low static on-resistance and high avalanche energy strength. This device provide excellent switching performance for UPS,DC-DC converters and AC-DC power supply.

### Features

- Low on-Resistance:  $R_{DS(on)}=0.24\Omega(\text{typ.})$
- Special Process Technology for high ESD Capability
- 100% Avalanche Test
- Good Stability and Uniformity with High  $E_{AS}$

### Applications

- UPS Applications
- DC-DC Converters and AC-DC Power Supply



### Absolute Maximum Ratings @ $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter		Ratings	Unit
$V_{DSS}$	Drain to Source Voltage		500	V
$V_{GSS}$	Gate to Source Voltage		$\pm 30$	V
$I_D$	Drain Current	$T_C=25^\circ\text{C}$	18	A
		$T_C=100^\circ\text{C}$	10.8	A
$I_{DM}$	Pulsed Drain Current	(Note1)	72	A
$P_D$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	235	W
	Derate above $25^\circ\text{C}$		1.78	W/ $^\circ\text{C}$
$E_{AS}$	Single Pulsed Avalanche Energy	(Note 2)	1298	mJ
$T_J$	Operating Junction Temperature Range		-55~+150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range		-55~+150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Ratings	Unit
$R_{th(J-C)}$	Thermal Resistance, Junction to case	0.56	$^\circ\text{C}/\text{W}$
$R_{th(J-A)}$	Thermal Resistance, Junction to Ambient	60	$^\circ\text{C}/\text{W}$

**Electrical Characteristics** @ $T_C=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain to Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	500	-	-	V
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	3.0	3.8	4.8	V
$R_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}, I_D=9\text{A}$	-	0.24	0.30	$\Omega$
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=V_{\text{DSS}}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to Source Leakage Current	$V_{\text{GS}}=V_{\text{GSS}}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA

**D-S Diode Characteristics and Maximum Rating** @ $T_C=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Maximum Drain to Source Diode Forward Current		-	-	18	A
$V_{\text{SD}}$	Drain-Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}, I_S=18\text{A}$	-	0.90	1.25	V
$T_{\text{rr}}$	Reverse Recovery Time		-	0.55	-	us
$Q_{\text{rr}}$	Reverse Recovery Charge	$V_{\text{GS}}=0\text{V}, I_S=18\text{A}, \frac{dI}{dt}=-100\text{A}/\text{us}$	-	5.5	-	$\mu\text{C}$

**Switching Characteristics** @ $T_C=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$t_{\text{d(on)}}$	Turn-on Delay Time	$I_D=18\text{A}, V_{\text{DD}}=250\text{V}, R_G=25\Omega$ (Note 3)	-	70	-	ns
$t_r$	Turn-on Rise Time		-	190	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time		-	100	-	ns
$t_f$	Turn-off Fall Time		-	100	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}, f=1.0\text{MHz}$	-	2500	-	pF
$C_{\text{oss}}$	Output Capacitance		-	400	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	40	-	pF
$Q_g$	Total Gate Charge	$I_D=18\text{A}, V_{\text{DS}}=400\text{V}$ $V_{\text{GS}}=10\text{V}$ (Note 3)	-	46	-	nC
$Q_{\text{gs}}$	Gate to Emitter Charge		-	14	-	nC
$Q_{\text{gd}}$	Gate to Collector Charge		-	22	-	nC

**Note:**

1. Repetitive rating: pulse-width limited by maximum junction temperature
2.  $L=8.0\text{mH}, I_{AS}=18\text{A}, V_{DD}=50\text{V}, V_G=10\text{V}, @T_C=25^\circ\text{C}$
3. Essentially independent of operating temperature typical characteristics

## Typical Performance Characteristics

Fig. 1. Typical on-Resistance Characteristics

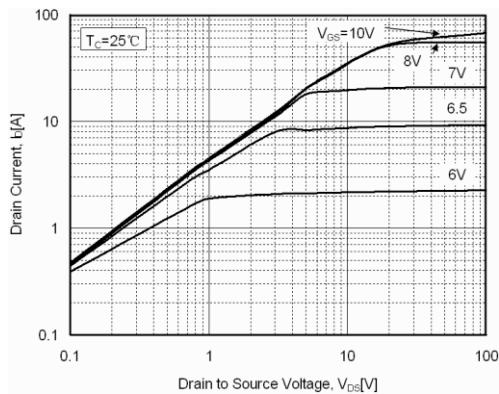


Fig. 2. Typical Transfer Characteristics

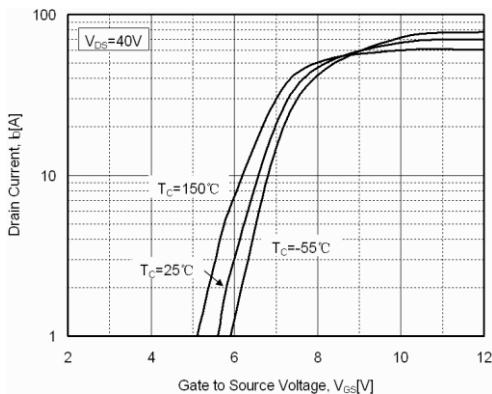


Fig. 3. Static on-Resistance vs.  $I_D$

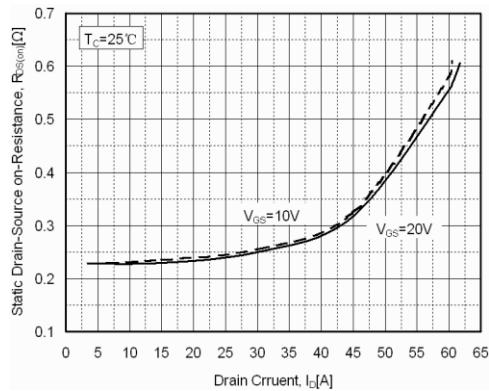


Fig. 4. Body Diode Forward Voltage vs.  $I_{DR}$

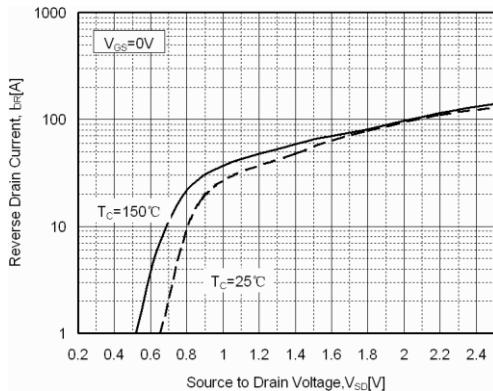


Fig. 5. Capacitance Characteristics

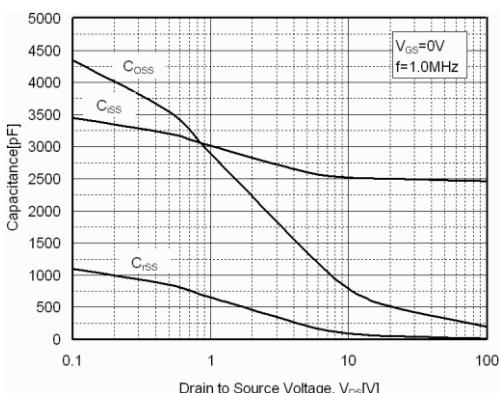
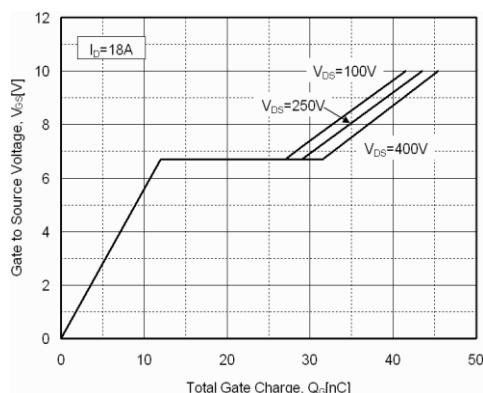


Fig. 6. Gate Charge Characteristics



## Typical Performance Characteristics

Fig. 7. Breakdown Voltage vs. Temperature

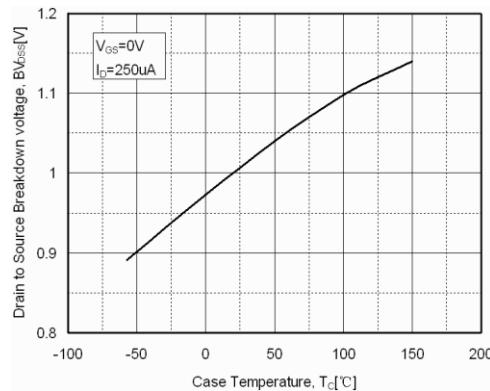


Fig. 8. Static on-Resistance vs. Temperature

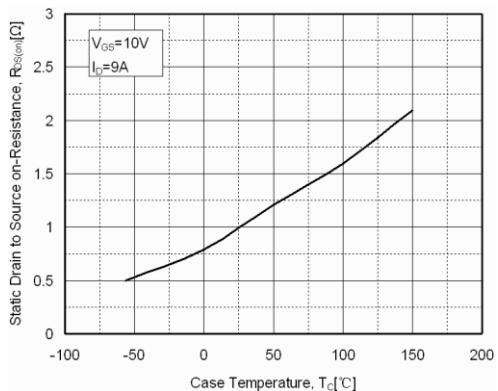


Fig. 9. Maximum Safe Operating Area

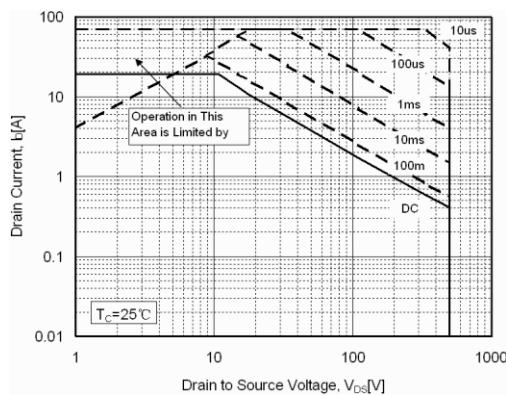


Fig. 10. Maximum Drain Current vs. Temperature

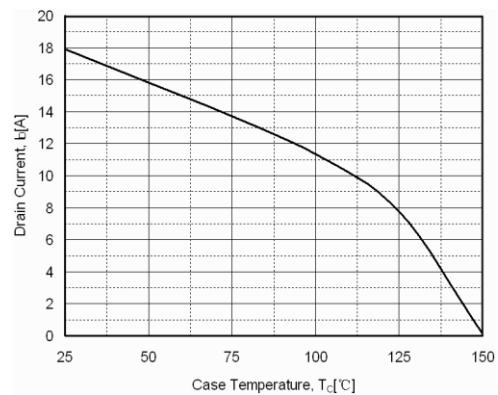
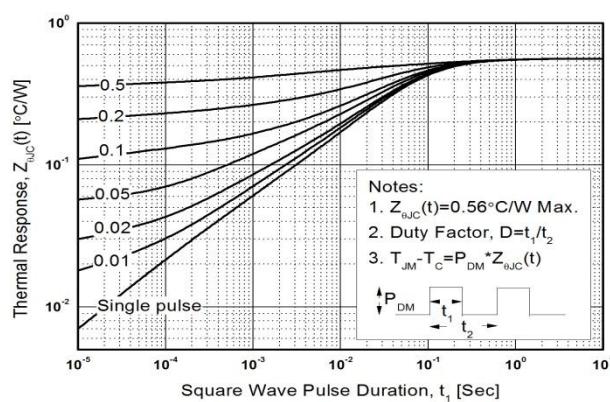


Fig. 11. Transient Thermal Response Curve



**Package Dimensions****TO-3PN**

(Dimensions in Millimeters)

